# Non-Magnetic MELF PIN Diode



MA4P7470F-1072T

Rev. V3

#### **Features**

- Non-Magnetic Package Suitable for MRI Applications
- Rectangular MELF SMQ Ceramic Package
- Hermetically Sealed
- Low R<sub>S</sub> for Lower Series Loss
- Long t<sub>L</sub> for Low Intermodulation Distortion
- Low C<sub>J</sub> for High Series Isolation
- High Average Incident Power Handling Capability
- RoHS\* Compliant

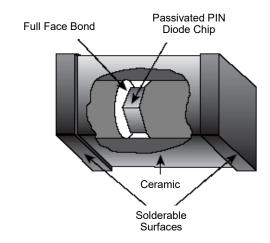
### **Applications**

MRI

### **Description**

The MA4P7470F-1072T is a surface mountable PIN diode in a non-magnetic Metal Electrode Leadless Faced (MELF) package. The device incorporates a time proven HIPAX technology to produce a low inductance ceramic package with no ribbons or whisker wires. The package utilizes a non-magnetic plating process to provide an extremely low permeability, hermetically sealed package. Incorporated in the package is a passivated PIN diode that is full face bonded on both the cathode and anode of the chip to maximize surface area for electrical and thermal resistance. MA4P7470F-1072T has been comprehensively characterized both electrically and mechanically to ensure repeatable and predictable performance.

The MA4P7470-1072T diode is well suited for use in low loss, low distortion, and high power switching circuits applicable for high magnetic field environments from HF through UHF frequencies. The lower thermal resistance of this device provides excellent higher average performance at RF power incident levels up to 200 watts CW. This device is designed to meet the most rigorous electrical and mechanical requirements of MRI environments.



#### **Designed for Automated Assembly**

MELF PIN diodes are designed for high volume tape and reel assembly. The rectangular package design provides for highly efficient automatic pick and place assembly techniques. The parallel flat surfaces are suitable for key jaw or vacuum pickup techniques. All solderable surfaces are tin plated and compatible with reflow and vapor phase soldering methods.

#### **Ordering Information**

Part Number	Package
MA4P7470F-1072T	Tape and Reel

<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



Rev. V3

### Electrical Specifications: +25°C

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Forward Voltage (V <sub>F</sub> )	I <sub>F</sub> = +100 mA	$V_{DC}$	_	_	1
Reverse Voltage (V <sub>R</sub> ) <sup>1</sup>	Ι <sub>R</sub> = -10 μΑ	$V_{DC}$	800	_	_
Total Capacitance (C <sub>T</sub> )	-100 V @ 100 MHz	pF	_	_	0.7
Series Resistance (R <sub>S</sub> )	+100 mA @ 100 MHz	Ω	_	_	0.8
Parallel Resistance (R <sub>P</sub> )	-10 V @ 100 MHz	kΩ	50	_	
Carrier Lifetime (t <sub>L</sub> )	+6 mA / -10 mA @ (50% - 90% Voltage)	μs	_	6.5	_
I-Region Length (μm)	_	μm	_	140	_
C.W. Thermal Resistance (q)	I <sub>H</sub> = 1A, I <sub>L</sub> = 10 mA, T = 1 ms	°C/W	_	_	13
Power Dissipation (W)	I <sub>F</sub> = +100 mA In free air With heatsink	W	_	_	4 12

<sup>1.</sup> The minimum specified  $V_R$  (Reverse Voltage) is sourced and the resultant  $I_R$  (Reverse Leakage Current) is measured to be <10  $\mu$ A.

# Absolute Maximum Ratings<sup>2,3</sup>

Parameter	Absolute Maximum
RF CW Incident Power	53 dBm
Forward DC Current	150 mA
Reverse DC Voltage	- 800 V @ -10 μA
Operating Temperature	-65°C to +125°C
Storage Temperature	-65°C to +150°C
Diode Junction Temperature	+175°C Continuous
Diode Mounting Temperature	+265 °C for 10 seconds

<sup>2.</sup> Exceeding any one or combination of these limits may cause permanent damage to this device.

# **Handling Procedures**

Please observe the following precautions to avoid damage:

### **Static Sensitivity**

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

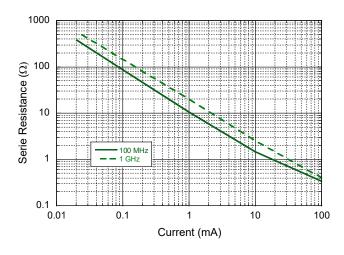
MACOM does not recommend sustained operation near these survivability limits.



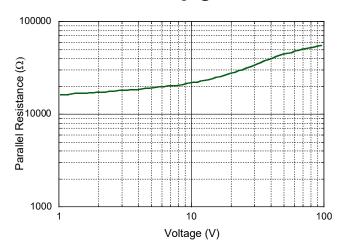
Rev. V3

# **Typical Electrical Performance**

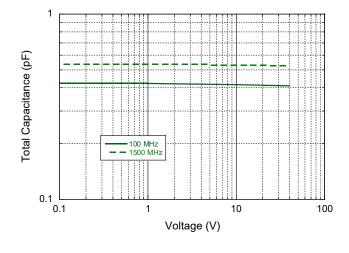
#### Series Resistance vs. Current



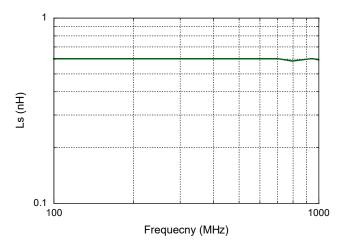
#### Parallel Resistance vs. Voltage @ 1.5 GHz



#### Total Capacitance vs. Voltage



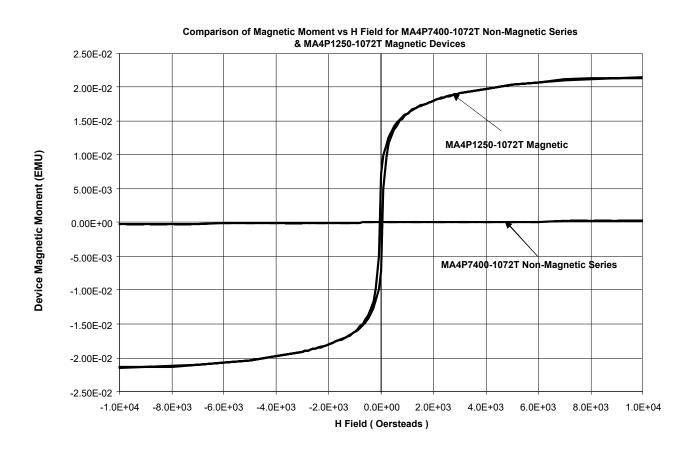
#### Ls vs. Frequency @ 50 mA





Rev. V3

## **Typical Non-Magnetic Performance**



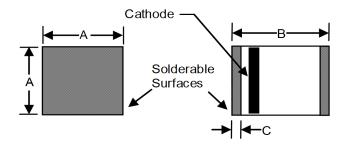
# Typical Magnetic Properties: Non-Magnetic (MA4P7470F-1072T) vs. Magnetic (MA4P1250-1072T)

Magnetic Property	MA4P7470F-1072T	MA4P1250-1072T
Saturation Moment (EMU) @ H = H <sub>MAX</sub> Oersted's	2.3 x E-4	2.1 x E-2
Remanence Moment (EMU) @ H = 0 Oersted's	4.2 x E-8	7.1 x E-3
Coercivity (Oersted's) @ EMU = 0 Moment	1	59.2



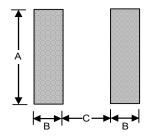
Rev. V3

### Outline (ODS -1072)



Dimension	inches		mm		
Dilliension	Min.	Max.	Min.	Max.	
Α	0.080	0.095	2.032	2.413	
В	0.115	0.135	2.921	3.429	
С	0.008	0.030	0.203	0.762	

## **Circuit Pad Layout (ODS-172)**



Dimension	inches	mm
Α	0.093	2.36
В	0.050	1.27
С	0.060	1.52

## **Environmental Screening Capability**

HIPAX devices are applicable for use in industrial and military applications and can be screened to meet the environmental requirements of MIL-STD-750, MIL-STD-202 as well as other military standards. The table below lists some of the MIL-STD 750 tests the device is designed to meet.

MIL-STD-750			
Test	Method	Description	
High Temperature Storage	1031	+150°C, for 340 Hours	
Temperature Shock	1051	-65°C to +125°C, 20 Cycles	
HTRB	1038	80% of rated V <sub>B</sub> , +150°C, for 96 Hours	
Moisture Resistance	1021	No Initial Conditioning, 85% RH, +85°C	
Gross Leak	1071 Cond. E	Dye Penetrant Visual	
Vibration Fatigue	2046	20,000 G's, 60 Hz, x, y, z axis	
Solderability	2026	Test Temperature = +245°C	

# Non-Magnetic MELF PIN Diode



MA4P7470F-1072T

Rev. V3

## MACOM Technology Solutions Inc. ("MACOM"). All rights reserved.

These materials are provided in connection with MACOM's products as a service to its customers and may be used for informational purposes only. Except as provided in its Terms and Conditions of Sale or any separate agreement, MACOM assumes no liability or responsibility whatsoever, including for (i) errors or omissions in these materials; (ii) failure to update these materials; or (iii) conflicts or incompatibilities arising from future changes to specifications and product descriptions, which MACOM may make at any time, without notice. These materials grant no license, express or implied, to any intellectual property rights.

THESE MATERIALS ARE PROVIDED "AS IS" WITH NO WARRANTY OR LIABILITY, EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHT, ACCURACY OR COMPLETENESS, OR SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES WHICH MAY RESULT FROM USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.